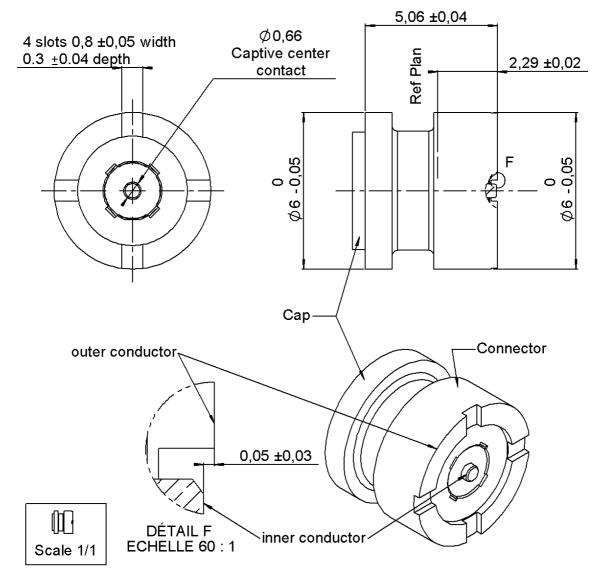
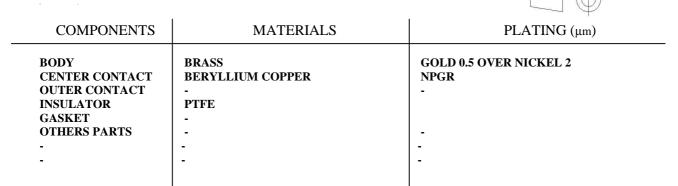
R222.408.350

Series : SMP

SMT TYPE-LIMITED DETEND REEL 500



All dimensions are in mm.



Issue: 0744 C

In the effort to improve our products, we reserve the right to make changes judged to be necessary.



R222.408.350

SMT TYPE-LIMITED DETEND REEL 500

Series: SMP

PACKAGING

Standard Unit Other 500 Contact us

SPECIFICATION

ELECTRICAL CHARACTERISTICS

 $\begin{array}{ccc} \text{Impedance} & & \textbf{50} \;\; \Omega \\ \text{Frequency} & & \textbf{0-18} \;\; \text{GHz} \end{array}$

VSWR 1.03 + 0,0100 x F(GHz) Maxi

Insertion loss

RF leakage

- (
NA - F(GHz) dB Maxi

RF leakage

Voltage rating 335 Veff Maxi Dielectric withstanding voltage Insulation resistance 500 Veff mini 500 M Ω mini

ENVIRONMENTAL

Operating temperature -65/+165 ° C

Hermetic seal NA Atm.cm3/s

Panel leakage NA

OTHER CHARACTERISTICS

Assembly instruction

Others:

MECHANICAL CHARACTERISTICS

Center contact retention

Axial force – Mating end
Axial force – Opposite end
Torque

6.7 N mini
6.7 N mini
NA N.cm mini

Recommended torque

Mating NA N.cm Panel nut NA N.cm

Mating life 500 Cycles mini

Weight **0,8200** g

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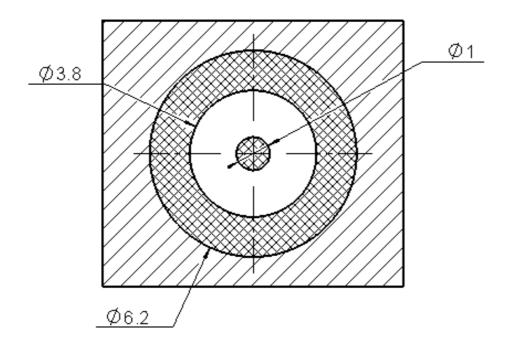


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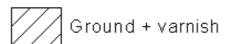
SMT TYPE-LIMITED DETEND REEL 500

Series: SMP

STANDARD PAD (RADIALL RECOMMANDATION)







- -The landing pad for center contact should be linked to the stripline using a filled via.
- -Upper and lower ground planes should be linked using vias.

Issue: 0744 C

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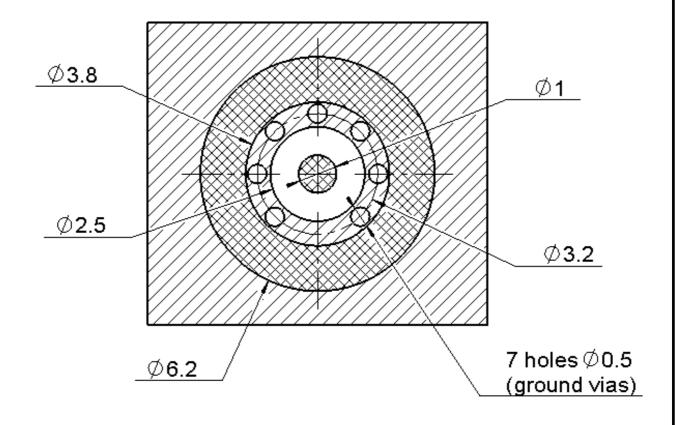


R222.408.350

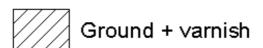
SMT TYPE-LIMITED DETEND REEL 500

Series: SMP

RT DUROID 6002 (30 mils) PAD (RADIALL RECOMMANDATION)



Land for solder past



-The landing pad for center contact should be linked to the stripline using a filled via.

-Upper and lower ground planes should be linked using vias.

Issue: 0744 C

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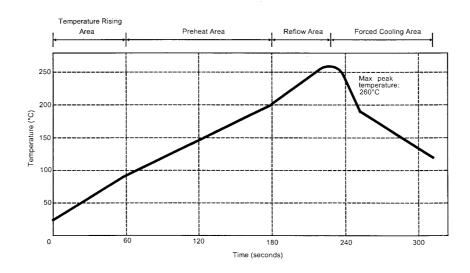
Series: SMP

SMT TYPE-LIMITED DETEND REEL 500

SOLDER PROCEDURE

- 1. Deposit solder paste 'SnAg4Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.
 - We advise a thickness of 150 μm (5.850 microinch). Verify that the edges of the zone are clean.
- 2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type. A video camera is recommended for positioning of the component. Adhesive agents must not be used on the receptacle.
- 3. This process of soldering has been tested with convection oven .Below please find ,the typical profile to use.
- 4. The cleaning of printed circuit boards is not obliged .
- 5. Verification of solder joints and position of the component by visual inspection.

TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to -4	°C/sec
Max dwell time above 100°C	420	sec

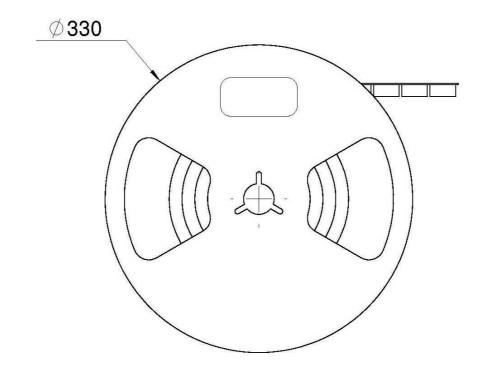
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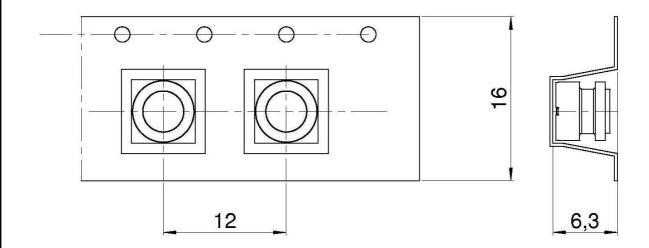
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RECEPTACLE R222.408.350

SMT TYPE-LIMITED DETEND REEL 500 Series : SMP





Issue: 0744 C

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